

RD Number: RD139

RD Title: TB67S141NG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CVCC	1	0.1 μ F 100V	—	—	Chip capacitor	3.2mmX1.6mm	
2	CVREF	1	0.1 μ F 100V	—	—	Chip capacitor	3.2mmX1.6mm	
3	CVM2	1	0.1 μ F 100V	—	—	Chip capacitor	3.2mmX1.6mm	
4	CVM1	1	100 μ F 50V	—	—	Electrolytic capacitor		
5	CVDD	1	10 μ F 50V	—	—	Electrolytic capacitor		
6	RERR	1	10k Ω 0.25W	—	—	Chip resistor	3.2mmX1.6mm	
7	RALM	1	10k Ω 0.25W	—	—	Chip resistor	3.2mmX1.6mm	
8	RMO	0	10k Ω 0.25W	—	—	Chip resistor	3.2mmX1.6mm	✓
9	ROSCM	0	10k Ω 0.25W	—	—	Chip resistor	3.2mmX1.6mm	✓
10	ROSCM	1	10k Ω 0.25W	—	—	Leaded resistor		
11	ROSCM	2	Socket pin	—	—	Socket pin		
12	RVF1	0	2.5k Ω 0.125W	—	—	Leaded resistor		✓
13	RVF1	2	Socket pin	—	—	Socket pin		
14	RVF2	0	2.5k Ω 0.125W	—	—	Leaded resistor		✓
15	RVF2	2	Socket pin	—	—	Socket pin		
16	ZD1	1	CMZ36	CMZ36(TE12L.Q)	TOSHIBA	Zener diode	M-FLAT	
17	ZD2	0	Not mount	—	—	Zener diode		✓
18	ZD3	0	Not mount	—	—	Zener diode		✓
19	PHASEA	0	Pin header 3P	—	—	Jumper	2.54mm pitch	✓
20		0	Jumper socket	—	—	Short pin	2.54mm pitch	✓
21	PHASEB	0	Pin header 3P	—	—	Jumper	2.54mm pitch	✓
22		0	Jumper socket	—	—	Short pin	2.54mm pitch	✓
23	INA1	1	Pin header 3P	—	—	Jumper	2.54mm pitch	
24		1	Jumper socket	—	—	Short pin	2.54mm pitch	
25	INA2	1	Pin header 3P	—	—	Jumper	2.54mm pitch	
26		1	Jumper socket	—	—	Short pin	2.54mm pitch	

27	INB1	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
28		1	Jumper socket	–	–	Short pin	2.54mm pitch	
29	INB2	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
30		1	Jumper socket	–	–	Short pin	2.54mm pitch	
31	STBY	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
32		1	Jumper socket	–	–	Short pin	2.54mm pitch	
33	BRAKE	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
34		1	Jumper socket	–	–	Short pin	2.54mm pitch	
35	JP_VCC	1	Pin header 2P	–	–	Jumper	2.54mm pitch	
36		1	Jumper socket	–	–	Short pin	2.54mm pitch	
37	VDD	1	Check terminal	–	–	Logic pin		
38	VM	1	Check terminal	–	–	Logic pin		
39	VCC	1	Check terminal	–	–	Logic pin		
40	ERR	1	Check terminal	–	–	Logic pin		
41	ALM	1	Check terminal	–	–	Logic pin		
42	PHASEA	1	Check terminal	–	–	Logic pin		
43	PHASEB	1	Check terminal	–	–	Logic pin		
44	INA1	1	Check terminal	–	–	Logic pin		
45	INA2	1	Check terminal	–	–	Logic pin		
46	INB1	1	Check terminal	–	–	Logic pin		
47	INB2	1	Check terminal	–	–	Logic pin		
48	STBY	1	Check terminal	–	–	Logic pin		
49	BRAKE	1	Check terminal	–	–	Logic pin		
50	VREF	1	Check terminal	–	–	Logic pin		
51	VCOM	0	Check terminal	–	–	Logic pin		✓
52	OUT_A+	1	Check terminal	–	–	Logic pin		
53	OUT_A-	1	Check terminal	–	–	Logic pin		
54	OUT_B-	1	Check terminal	–	–	Logic pin		
55	OUT_B+	1	Check terminal	–	–	Logic pin		
56	GND1	1	Check terminal	–	–	Logic pin		
57	GND2	1	Check terminal	–	–	Logic pin		
58	GND3	1	Check terminal	–	–	Logic pin		
59	GND4	1	Check terminal	–	–	Logic pin		
60	GND5	1	Check terminal	–	–	Logic pin		

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